

SOT1063-1

plastic very thin fine-pitch ball grid array package; 48 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA48
Package type industry code	VFBGA48
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	---
Mounting method type	S (surface mount)
Issue date	17-3-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	0.8	-	0.9	1	mm
A ₂	package height	0.65	-	0.7	0.75	mm
n ₂	actual quantity of termination	-	-	48	-	



2. Package outline

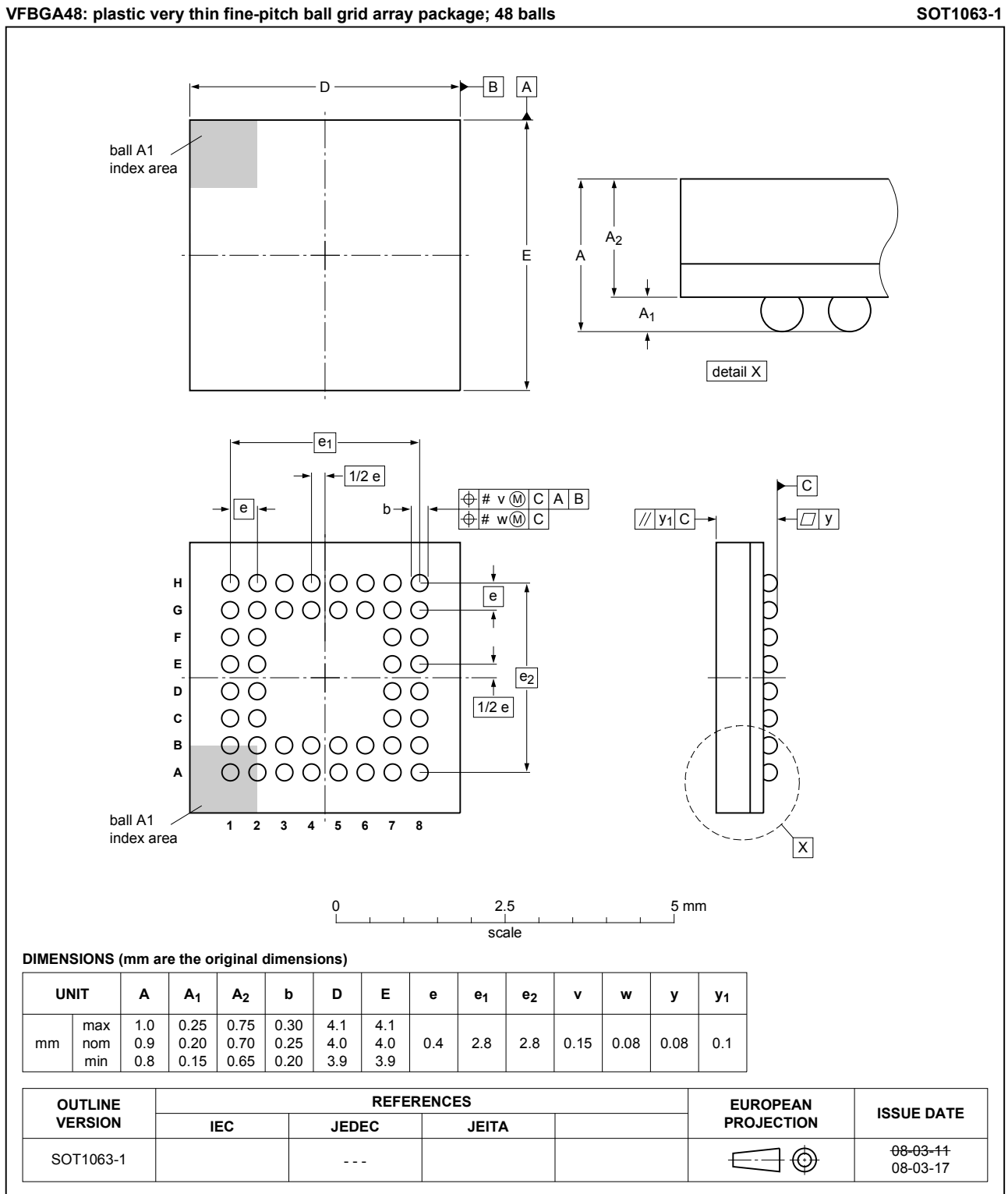
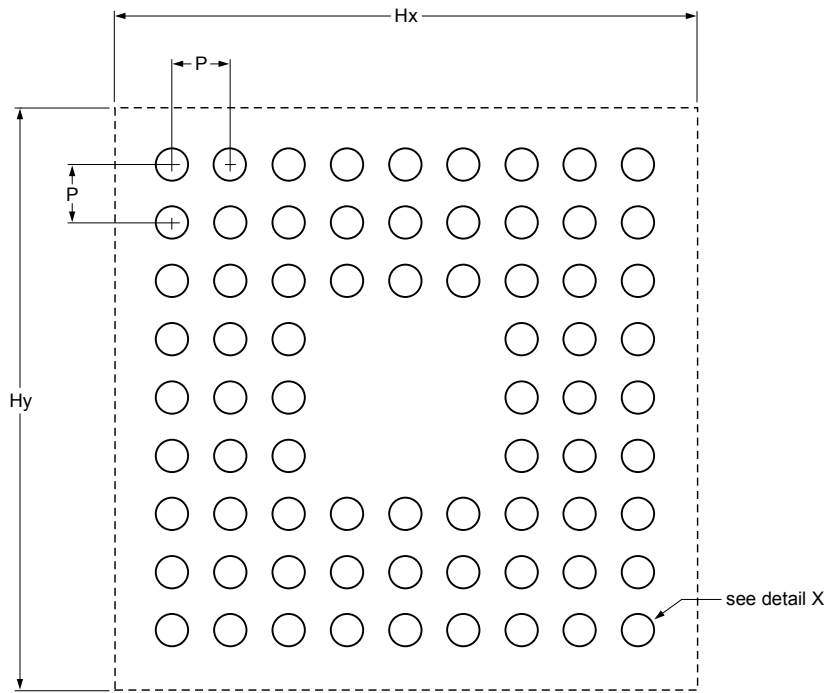


Fig. 1. Package outline VFBGA48 (SOT1063-1)




3. Soldering

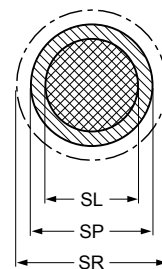
Footprint information for reflow soldering of VFPGA48 package

SOT1063-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.40	0.250	0.275	0.350	4.400	4.400

sot1063-1_fr

Fig. 2. Reflow soldering footprint for VFPGA48 (SOT1063-1)

4. Legal information

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